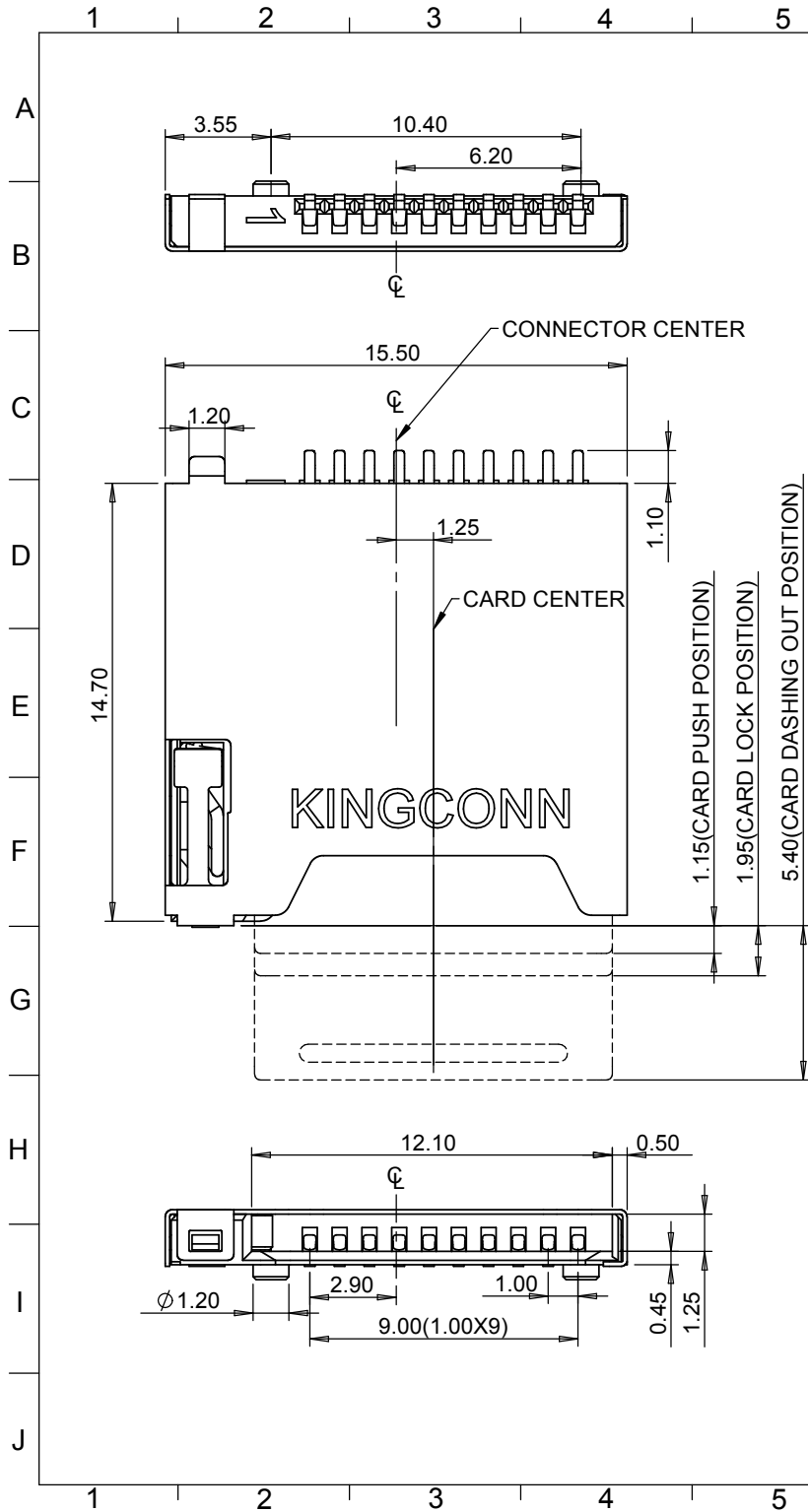
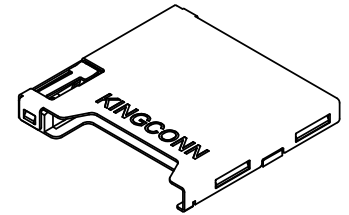
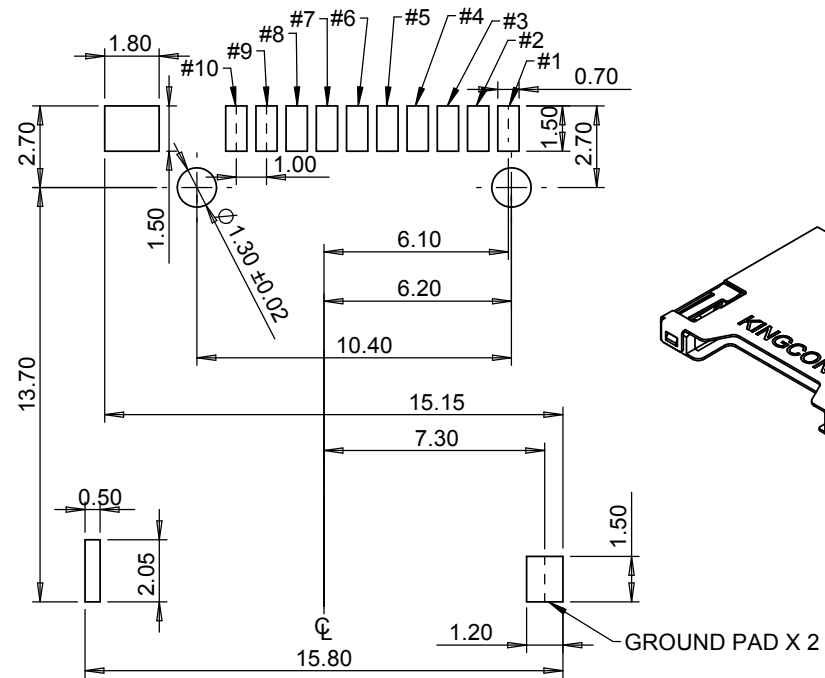


- NOTES:
- MATERIAL:
INSULATOR: HIGH TEMPRATURE THERMOPLASTIC,
UL94V-0, BLACK
CONTACT: PHOSPHOR BRONZE
 - PLATING:
CONTACT AREA: 10 μ " Au Plated OVER Ni
SOLDER AREA: Tin Plated OVER Ni
 - PART NO: MMCP-B0-X010

PACKING:
0 : TRAY
1 : TAPE&REEL



Pin Assignment:

#1	DTA2
#2	DAT3
#3	CMD
#4	CD
#5	VDD ₁
#6	VDD ₂
#7	CLK
#8	VSS ₂
#9	DAT0
#10	DAT1

WITHOUT CARD

CD $\circ$ $\circ$ GROUND

MMCmicro CARD INSERTED

CD $\circ$ — — $\circ$ GROUND

GENERAL TOLERANCE

X $\pm$ 0.50	X $^{\circ}$ $\pm$ 5 $^{\circ}$
.X $\pm$ 0.30	.X $^{\circ}$ $\pm$ 2 $^{\circ}$
.XX $\pm$ 0.20	.XX $^{\circ}$ $\pm$ 1 $^{\circ}$
	.XXX $^{\circ}$ $\pm$ 0.5 $^{\circ}$

KINGCONN 皇海科技股份有限公司

名稱(TITLE)
MMCmicro Push-Push Connector

單位(UNIT) mm	料號(PART NO.) MMCP-B0-X010	圖號(DWG NO.) MMCP-B0-X010-D
審核(APPROVAL)	核對(CHECKED)	製圖(DRAWN)
比例 SCALE 4 : 1	張數 SHEET 1 / 1	更改 REV D

